



Material Content Data Sheet



Sales Product Name		BTS5030-1EJA		Issued		9. January 2019		
MA#		MA002296624						
Package		PG-DSO-8-43		Weight*		84.45 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.062	2.44	2.44	24418	24418
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		111	
	non noble metal	zinc	7440-66-6	0.038	0.04		445	
	non noble metal	iron	7439-89-6	0.752	0.89		8903	
wire	non noble metal	copper	7440-50-8	30.529	36.15	37.09	361504	370963
	non noble metal	copper	7440-50-8	0.470	0.56	0.56	5562	5562
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.11		1145
	plastics	epoxy resin	-	4.447	5.27		52656	
	inorganic material	silicondioxide	60676-86-0	43.791	51.86	57.24	518541	572342
leadfinish	non noble metal	tin	7440-31-5	0.814	0.96	0.96	9637	9637
plating	noble metal	silver	7440-22-4	0.726	0.86	0.86	8597	8597
glue	plastics	epoxy resin	-	0.125	0.15		1484	
	noble metal	silver	7440-22-4	0.591	0.70	0.85	6997	8481
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com